

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Haruhiko Watanabe</td> <td>12/28/2007</td> </tr> <tr> <td>Yoshinori Kurosawa</td> <td>12/28/2007</td> </tr> <tr> <td>Takashi Araki</td> <td>12/28/2007</td> </tr> </tbody> </table>		Name	Execution Date	Haruhiko Watanabe	12/28/2007	Yoshinori Kurosawa	12/28/2007	Takashi Araki	12/28/2007
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Haruhiko Watanabe	12/28/2007								
Yoshinori Kurosawa	12/28/2007								
Takashi Araki	12/28/2007								
RECEIVING PARTY DATA									
Name:	Dowa Electronics Materials Co., Ltd.								
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku,								
City:	Tokyo								
State/Country:	JAPAN								
Postal Code:	101-0021								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11813321</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11813321				
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CORRESPONDENCE DATA									
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Masao Yoshimura								
Total Attachments: 1 source=Assignment_signed_071228#page1.tif									

OP \$40.00 11813321

PATENT

500605285

REEL: 021303 FRAME: 0808

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

INFRARED EMITTING DIODE AND METHOD OF ITS MANUFACTURE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on July 3, 2007, (Application No. 11/813,321); and

WHEREAS, DOWA ELECTRONICS MATERIALS CO., LTD, a corporation in Japan, whose post office address is 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Haruhiko WATANABE	Assignor's Signature <i>Haruhiko Watanabe</i>	Date December 28, 2007
Address c/o DOWA ELECTRONICS MATERIALS CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku Tokyo 101-0021, Japan		Citizenship Japan
Full Name of Second Assignor Yoshinori KUROSAWA	Assignor's Signature <i>Yoshinori Kurosawa</i>	Date December 28, 2007
Address c/o DOWA ELECTRONICS MATERIALS CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan		Citizenship Japan
Full Name of Third Assignor Takashi ARAKI	Assignor's Signature <i>Takashi Araki</i>	Date December 28, 2007
Address c/o DOWA ELECTRONICS MATERIALS CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan		Citizenship Japan
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		